

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 7,128,806 B2
APPLICATION NO. : 10/689783
DATED : October 31, 2006
INVENTOR(S) : Nguyen et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Title Page, Item [57], ABSTRACT, Line 4: Change "comprising-a" to --comprising a--

Column 2, Line 67: Insert a semicolon after "ring"

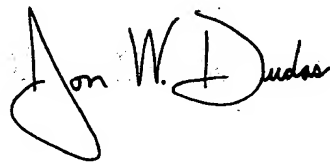
Column 6, Line 62: Change "MxPTM" to --MxPTM--

Column 7, Lines 41-51: The paragraph beginning on line 41 should read:

--The supporting apparatus and substrate handler blade 300 described above may also be taken advantage of in a substrate processing system 410 providing support for a substrate. The substrate processing system 410 may include a transfer chamber 414, at least one processing chamber 160 with a substrate support member 100 with a support surface and a capture ring coupled to the support surface, the capture ring adapted to receive a substrate, and a substrate handler 418 disposed in the transfer chamber 414. The substrate handler 418 preferably has a substrate handler blade 300 described above. The process chambers are preferably plasma etch chambers.--

Signed and Sealed this

Twenty-seventh Day of March, 2007

A handwritten signature in black ink, appearing to read "Jon W. Dudas". The signature is stylized with a large, looped initial "J" and a distinct "D" at the end.

JON W. DUDAS
Director of the United States Patent and Trademark Office